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FULLY AUTOMATIC PROBER UF190/UF200

DEVICE CREATION GUIDE

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Chapter 1. Setting Parameter

It needs to set several parameters.

- ➢ Device name
- Device information
- Probe card information
- ➢ Mapping information

Setting Device name

1. Push [DEVICE PARAMETER CHANGE] Switch.



2. Push [DEVICE] Switch.

***** DEVICE PARAMETER SETTTINGS ****	*	
PAGE 1 / 6	PRINTOUT	
Device	: MDF SYSTEM MODE CHANGE	
Wafer Size	: 6 inch ATTRIBUTE DATA DISPLAY	
Index Size X	: 5563.130000 um STORE	
Index Size Y	: 5561.260000 um	
Flat/Notch Direction (deg)	: 0 deg	
CANCEL	PREVIOUS NEXT PAGE PAGE	

3. Type DEVICE name and push [ENT] Switch.



4. Push [NEW DEVICE] Switch.

*****	EVICE DATA RESTORE ****	
DEVICE	: JL061	
ACCESSING	: HD, FD. GROUP MANAGEMENT	DEVICE LIST REFERENCE
	EXPECTED DEVICE DATA NOT FOUND !!	
CANCEL	NEW DEVICE	ENT

5. If you need to copy part of old Device file, you should choose data. And then push [EXECUTE] Switch.

*** NEW DEVICE DATA ALIGNMENT IMAGE DATA PROBING	A COPY *** SAMPLING DIE DATA PAD	
DIE DATA : NO	POSITION DATA : NO	
Select COPY DATA		
CANCEL		EXECUTE

ALIGNMENT IMAGE DATA	: wafer image data (for wafer alignment)
PROBING DIE DATA	: wafer map data
SAMPLING DIE DATA	: sample probing die position data
PAD POSITION DATA	: registered pad position data

<---- FOR EXAMPLE >>> In case of modifying wafer map data, you can copy [IMAGE DATA] [PAD POSITION DATA].

Setting Device Information

1. Type Device data (wafer size, die size, flat or notch direction).



Setting Probe card Information

1. Setting [Probe Card Thickness] and [Needle Height on Probe Card] parameter. See detail "USER'S MANUAL ON CONTROL PARAMETERS".

***** DEVICE PARAMETER SETTTINGS ****	*			DATA
PAGE 1 / 5 NEEDLE ALIGNMENT DAT	A SETTING		F F	PRINTOUT
Needle Alignment die Setting 0: Absolute Coordinates 1: Relative Coordinates	:	1		SYSTEM MODE CHANGE
Needle Alignment Die Coordinate X	:	0	AT L	TTRIBUTE DATA DISPLAY
Needle Alignment Die Coordinate Y	:	0		DATA STORE
Probe Card Thickness (0 - 20mm) 0:when side of fitting up card base is in needle side	:	1.6 mm		
Needle Height on Probe Card (2—15mm)	:	2.8 mm		SETTING END
CANCEL	PREVIOU	S NEXT		
MENU	PAGE	PAGE		

2. Push[PREVIOUS MENU] Switch. Look for [MAPPING SETTINGS]parameter. Push that Switch.



Setting Mapping Information

1. Select method of making map data.

***** DEVICE PARAMETER SETTTINGS *****			
PAGE 1 / 3 MAPPING SETTINGS			FKINTOUT
Test Area Determination 0: Wafer Shape Width 1: WF. Radius 2: Range Directlly 3: 4-Pt. Data-In	:	3	SYSTEM MODE CHANGE
Wafer Margin	:	0 mm	ATTRIBUTE DATA DISPLAY
Test Die Margin	:	100 %	DATA STORE
ON WAFER Determination 0: Calculation 1: Edge Sensor 2: Calculation & Edge sensor		0	
Test Die Determination 0: Data–In of Die 1: Data–In of Area	:	1	SETTING
CANCEL PREVIOUS P MENU	REVIO PAGE	DUS NEXT	

2. Push [SETTING END] Switch after choosing method.



Chapter 2. Register Image Data

It is possible to choose how to register Image Data, by Auto mode or Manual mode.

- > Choose register mode
- > Register image data by Auto mode
- > Register image data by Manual mode

Choose Register mode

1. Push [DEVICE PARAMETER CHANGE] Switch.



2. Push [NEXT] Switch. Look for [ALIGNMENT DATA Setting] parameter. Push that Switch.



3. Choose AUTO mode or MANUAL mode. And then push [SETTING END].



Registering Image Data by AUTO mode

1. Load wafer.

Prober stops and buzzer sounds. Push J/S. Move CROSS MARK to street cross by J/S and then push [DATA IN] Switch.

			LIGHTING CHANGE INTENSITY	
			UP INTENSITY DOWN MAG	
			CHANGE	
Push <data in≻="" sw.<="" td=""><td>at STREET CR</td><td>285</td><td></td><td></td></data>	at STREET CR	285		
INTERRUPT			DATA IN	F

Registering Image Data by MANUAL mode

1. Load wafer.

Prober stops and buzzer sounds.

Push J/S.

Move CROSS MARK to street cross by J/S and then push [DATA IN] Switch.

			LIGHTING CHANGE INTENSITY UP INTENSITY DOWN MAG. CHANGE	
Push ≺DATA IN⊳ SW.	at STREET CRO	\$\$ _ !!		/
INTERRUPT				

2. Push [DATA IN] Switch at reference point.

	LIGHTING CHANGE INTENSITY UP INTENSITY DOWN
Push <data in=""> SW. at REFERENCE MODEL !!</data>	AUTO BRIGHTNESS SETTINGS AUTO MODEL SELECT
INTERRUPT	DATA IN

3. Prober switches high magnification. Look for unique point inside die And then push [DATA IN] Switch.





Chapter 3. Register Pad Position Data

- > Register probing area in die
- > Register pad position
- Confirm pad position

Register probing area in die





Registering Pad Position

We recommend...



1. Move WINDOW to Pad by J/S. Change WINDOW size to Pad size by arrow Switch. Push [DATA IN] Switch. Move next pad by J/S.

(It is possible to check how many pads registered.)



[WINDOW TRAVL.STEP CAHNGE] [Arrow key]	: Allows you to change Cross mark moving speed.: Allows you to change WINDOW size.
[WINDOW TRAVL.MODE CHANGE	(Cross mark moves.) E] : Allows you to move Cross mark position.
[PAD SEARCH]	: Allows you to search pad by automatic.

2. After you register pad position data, push [PAD REGIST. END] Switch.



3. If you need to confirm Registered Pad Position, push [PAD CONFIRM] Switch.



If you need to start needle alignment, push [EXIT] Switch.

Confirm Pad Position

- Revistered Pad 2.8 Pad No.: 2.8
- 1. Push [NEXT PAD] or [PREVIOUS PAD] Switch. Registered window is moved by that Switch.

- 2. After confirmation, push [CANCEL] Switch.
- 3. Push [EXIT] Switch.

CANCEL

							LIGHTING	
							CHANGE	
							INTENSITY	
							UP	
							INTENSITY	
							DOWN	
							MAG.	
							CHANGE	
								1
							NEEDLE	
Select nee	dle inspec	tion proce	ssing MEN	J !!			MAINTE.	
								[
	PAD	PAD	PAD	NEEDLE	NDLE.INSP.	REFERENCE	EVIT	•
	REGIST.	SELECT	CONFIRM	INSPECTION	CHANGE	CORRECT	LAIT	

PREVIOUS

NEXT



Chapter 4. Making Map Data

- ➢ Wafer Shape Width mode
- ➢ Wafer Radius mode
- ➢ Range Directly mode
- > 4 Pt data in mode

Instructions for switches

X: 128 Y: 128 DIE MOVE MODE : OFF					
	LIGHTING				
	CHANGE				
	INTENSITY				
	UP				
	INTENSITY				
	DOWN				
	PRINT				
	OPERATION				
	SETTINGS				
Move die which corrected attribute to center of display and					
correct the attribute !!	MAP ATRIB. SETTING END				
MANUAL MOVING MARKING SKIP NEEDLE NORMAL MODE INSPECTION UNLOAD CHANGE DIE DIE DIE DIE DIE	MAP DISP.MODE CHANGE				

[MOVING MODE CHANGE]SW: Allows you to see each corner.[MARKING DIE] SW.: Allows you to set Marking(Inking) die.[SKIP DIE]SW.: Allows you to set Skip die.[NEEDLE INSPECTION DIE] SW.: Allows you to set Needle Inspection die.[NORMAL DIE] SW.: Allows you to set Normal(Probing) die.[MAP DISP.MODE CHANGE] SW.: Allows you to see whole map.[MAP ATRIB.SETTING END] SW.: Allows you to finish making map.

Wafer Shape Width Mode

1. Prober stops and buzzer sounds, after needle alignment. Push J/S.

Move CROSS MARK to die by J/S as you want to modify die (skip, marking, probing). This time you can only use the INDEX mode.



2. If you want to see the whole map, push [MAP DISP.MODE CHANGE] Switch.



3. After you confirm the map, push [MAP ATRIB. SETTING END] Switch.

Wafer Radius Mode

1. Prober stops and buzzer sounds, after needle alignment. Push J/S.

Move CROSS MARK to die by J/S as you want to modify die (skip, marking, probing). This time you can only use the INDEX mode.



2. If you want to see whole map, push [MAP DISP.MODE CHANGE] Switch.



3. After confirm map, push [MAP ATRIB. SETTING END] Switch.

Range Directly Mode

 Prober stops and buzzer sounds, after needle alignment. Push J/S. Move CROSS MARK to the top of the left side of wafer map.

Push [DATA IN] Switch.

This time you can only use the INDEX mode.



2. CROSS MARK is moved to right side automatically.

Push [DATA IN] Switch, after confirming that the die is right side die.



3. CROSS MARK is moved side by side. Push [DATA IN] Switch row by row. After CROSS MARK reaches the bottom row, push [MAP CREATION END] Switch.



4. Move CROSS MARK to die by J/S as you want to modify die (skip, marking, probing). This time you can only use the INDEX mode.

X: 128 Y: 128 DIE MOVE MODE: OFF	
	LIGHTING
	CHANGE
	INTENSITY
	UP
	INTENSITY
	DOWN
	DDTNT
	TIXINI
	OPERATION
	SETTINGS
Move die which corrected attribute to center of display and	
correct the attribute !!	MAP ATRIB.
	END
MANUAL MOVING MARKING SKIP NEEDLE NORMAL	
UNLOAD CHANGE DIE DIE DIE DIE DIE	CHANGE

5. If you want to see the whole map, push [MAP DISP.MODE CHANGE] Switch.



6. After confirming map, push [MAP ATRIB. SETTING END] Switch.

4 Point Data In Mode

 Prober stops and buzzer sounds, after needle alignment. Push J/S.
 Move CROSS MARK to left side of wafer map. Push [DATA IN] Switch.

This time you can only use the INDEX mode.

DIE MOVE MC Move die at push <data i<="" th=""><th>DDE : OFF</th><th>to center of displa</th><th>y and</th><th>LIGHTING CHANGE INTENSITY UP INTENSITY DOWN DPERATION SETTINGS</th><th></th></data>	DDE : OFF	to center of displa	y and	LIGHTING CHANGE INTENSITY UP INTENSITY DOWN DPERATION SETTINGS	
MANUAL UNLOAD	MOVING MODE CHANGE		MAP CREATION RETRY	DATA IN	

2. Move CROSS MARK to top of wafer map. Push [DATA IN] Switch. This time you can only use the INDEX mode.





3. Move CROSS MARK to bottom of wafer map. Push [DATA IN] Switch. This time you can only use the INDEX mode.

DIE MOVE MODE : OFF	
	LIGHTING
	CHANGE
	INTENSITY
	UP
	INTENSITY
	DOWN
	OPERATION
	SETTINGS
Move die at lower side of map to center of display and	
push <data in=""> SW. !!</data>	
MANUAL MOVING	
UNLOAD CHANGE CREATION RETRY	UATA IN



4. Move CROSS MARK to right side of wafer map. Push [DATA IN] Switch. This time you can only use the INDEX mode.

DIE MOVE MODE : OFF	
	LIGHTING
	CHANGE
	INTENSITY
	UP
	INTENSITY
	DOWN
	DPERATION
	SETTINGS
Move die at right side of man to center od display and	
push <data in=""> SW. !!</data>	
MANUAL	
MODE CREATION RETRY	DATA IN



5. Move CROSS MARK to die by J/S as you want to modify die (skip, marking, probing). This time you can only use the INDEX mode.



6. If you want to see the whole map, push [MAP DISP.MODE CHANGE] Switch.



7. After confirming map, push [MAP ATRIB. SETTING END] Switch.



Chapter 5. Save Device File Data

Instructions for saving device files

1. Check DEVICE name. If you need to change DEVICE name, push [DEVICE :] Switch. and type new DEVICE name.





Chapter 6. Sequence Back

Instructions for Sequence Back Switch.

***** SEQUENCE BACK SELECTION *****	
WAFER ALIGNMENT RETRY	
NEEDLE POSI. ADJUSTMENI REIRY	
NEEDLE POSI. • HEIGHT ADJUSTMENT RETRY	
CANCEL	EXECUTE

[WAFER ALIGNMENT RETRY]

[NEEDLE POSI. ADJUSTMENT RETRY] [MAP CONFIRMATION RETRY] [NEEDLE POSI. HIGHT ADJUSTMENT RETRY] : Prober does needle alignment again.

- : Prober does wafer alignment again and starts probing.
- : It adjustments needle position again.
- : Modifies wafer map.

Example (How to use Sequence Back Function)

> Wafer Alignment Retry

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>> Stop probing.
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>> Push [SEQUENCE BACK SETTINGS] Switch.



>> Push [WAFER ALIGNMENT RETRY] Switch.

